

Features

- Input voltage range: 2.5V ~ 29V
- Low on-resistance: typical 23mΩ
- Fixed 5.8V over voltage protection (OVP) threshold
- Super-fast OVP response time: typical 100ns
- Over temperature protection (OTP)
- Robust ESD and surge immunity capability $HBM > \pm 2KV$
 - $CDM > \pm 1kV$
- Tiny 6-bumps WLCSP 1.19mm x 0.87mm

Applications

Smart Phone, AR/VR Device, Tablet PC, Wearable etc.

General Description

YHM2008 over-voltage protection devices feature a low $23m\Omega$ (TYP) on-resistance high current integrated MOSFET which actively protect low-voltage systems against voltage supply faults up to +29VDC. An input voltage exceeding the over-voltage threshold will cause the internal MOSFET to turn off, preventing excessive voltage from damaging downstream devices.

The over-voltage protection threshold is 5.8V, response time is 100ns.

Additionally, YHM2008 internal switch supports 10Mbps digital signal communication when powered by VCOM pin.

YHM2008 is available in tiny 6-bumps WLCSP 1.19mm x 0.87mm, and operates over an ambient temperature range of -40°C to +85°C.



Typical Application



Fig 1. VBUS OVP Application Diagram



Internal Block Diagram



Fig 3. YHM2008 Functional Block Diagram



Pin Configurations



Fig 4. YHM2008 WLP-6 Pin Assignment (Top Through View)

YHM2008 WLP Pin Descriptions

Bump	Name	Description		
A1, B1	OUT	Power output.		
A2, B2	IN	Power Input.		
C1	GND	Device Ground.		
C2	VCOM	Connect to GPIO for communication or connect to ground if not used communication function.		



1. Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter			Max.	Unit
VI	IN to GND	-0.3	31	V	
Vout	OUT to GND	-0.3	V _{IN} +0.3	V	
V _{NC}	NC to GND	-0.3	6.0	V	
l _{in}	Switch I/O Current (Continuous)		4.0	А	
t _{PD}	Total Power Dissipation at $T_A = 25^{\circ}C$			W	
T _{STG}	Storage Temperature Range	-65	+150	°C	
TJ	Maximum Junction Temperature		+150	°C	
T∟	Lead Temperature (Soldering, 10 Seconds)		+260	°C	
θ _{JA}	Thermal Resistance, Junction-to-Ambient (1-in. Pad of 2-oz. Copper)			100	°C/W
ESD	Human Body Model, ANSI/ESDA/JEDEC JS-001-2012 All Pins		2.0		kV
	Charged Device Model, JESD22-C101	All Pins	1.0		

Note 1. Refer to JEDEC JESD51-7, use a 4-layerboard



2. Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance.

Parameters	Min.	Max.	Unit
Supply Voltage: V _{IN}	2.5	29	V
Supply Voltage: V _{VCOM}	1.6	5.5	V
Ambient Operating Temperature, T _A	-40	85	°C
V _{IN} Capacitor (No capacitor for communication function)	0.1		μF
Vout Load Capacitor (No capacitor for communication function)	1	100	μF
Operating Temperature Range	-40	85	°C

3. Detailed Electrical Characteristics

VIN = 2.5V to 29V, CIN = 0.1µF, T_A = -40°C to +85°C, typical values are at VIN = 5V, IIN ≤ 3A, T_A = +25°C, unless otherwise noted.

PARAMETER	SYMBO	CONDITION	MIN	TYP	MAX	UNIT	
INPUT OPERATION							
Input Voltage Range	VIN		2.5		29	V	
Input Supply Current	lin	V _{IN} = 5V		45		μA	
Under-Voltage Lockout	$V_{\text{IN}_\text{UVLO}}$	V _{IN} rising		2.35		V	
Under-Voltage Lockout Hysteresis	V _{IN_HYS}			20		mV	
OVER-VOLTAGE							
OVLO threshold	VIN_OVLO		5.6	5.8	6.0	V	
OVLO Hysteresis				140		mV	
Switch On-Resistance	Ron	V _{IN} = 5V, I _{OUT} = 0.5A, T _A = +25℃		23	40	mΩ	
TIMING CHARACTERISTICS							
Debounce Time	tdeb	Time from V_{IN} > 2.5V to the time V_{OUT} starts rising		16		ms	
Switch Turn-On Time	ton	$\label{eq:VIN} \begin{array}{l} V_{IN} = 5V, \ R_L = 100\Omega, \ C_{LOAD} = 100uF, \ V_{OUT} \\ from \ 0.1 \times V_{IN} \ to \ 0.9 \times V_{IN} \end{array}$		0.4		ms	
Switch Turn-Off Time	toff	$V_{IN} > V_{IN_OVLO}$ to $V_{OUT} = 0.9 \times V_{IN}$, RL = 100 Ω , V_{IN} rising at 10V/µs		100		ns	
THERMAL SHUTDOWN							
Thermal Shutdown				150	_	°C	
Thermal Shutdown Hysteresis				30		°C	

Note 1: This parameter is guaranteed by design and characterization; not production tested.



4. Detailed Description

4.1 General Introduction

YHM2008 over-voltage protection devices feature a low $23m\Omega$ (TYP) on-resistance high current integrated MOSFET which actively protect low-voltage systems against voltage supply faults up to +29VDC. An input voltage exceeding the over-voltage threshold will cause the internal MOSFET to turn off, preventing excessive voltage from damaging downstream devices.

The over-voltage protection threshold is 5.8V, response time is 100ns.

4.2 UVLO (Under-Voltage Lockout)

The device has a built-in under-voltage lockout (UVLO) circuit. When VIN is rising, the output remains disconnected from the input until VIN voltage is above 2.35V (TYP). This circuit has a 20mV hysteresis to provide noise immunity to transient conditions.

4.3 OVLO (Over-Voltage Lockout)

When the voltage at the input exceeds the programmed over-voltage trip point, the device immediately turns off the internal switch disconnecting the load from the abnormal voltage, preventing damage to downstream components. The OVLO threshold is fixed 5.8V.



4.4 USB On-The-Go (OTG) Operation

During OTG operation, the YHM2008 is initially disabled and the power FET's bulk diode is forward biased. The bulk diode represents ~0.7V drop across the device, which remains until the VIN voltage increase past 2.5 V, when the device is fully enabled. While the device is disabled and the body diode is forward biased, the max DC current through the diode is 1.8A. This current is limited by the thermal performance of the device $(0.7V \times 2.1A = 1.48W)$.

This is purely a transitionary condition as once the voltage at IN exceeds the UVLO voltage of 2.35V (TYP) and the debounce time of 15ms has elapsed, the main power switch will turn fully on, significantly reducing the voltage drop from OUT to IN.

4.5 Communication functionality

Both IN and VCOM may supply YHM2008. YHM2008 would be powered by VCOM if VCOM voltage is higher than 1.5V. By this, YHM2008 supports digital signal transmission through IN and OUT when the device is powered by VCOM. Typically, VCOM is recommended to be driven by GPIO typically. It is necessary to remove input and output capacitor when communication is required. If not use communication function, VCOM should be connected to ground.





4.6 Thermal Protection

The internal FET turns off when the junction temperature exceeds +150°C (TYP). The device exits thermal shutdown after the junction temperature cools down by 30°C (TYP).



Package Dimensions

WLCSP-6 1.19mm x 0.87mm x 0.574mm





Ordering Information

Part Number	Temp Range	Pin Package	Top Mark	MOQ
YHM2008W6T	-40°C to 85°C	6 WLCSP	YWW LL8	3000

T = Tape and reel.

YWW: Date Code. Y = year, WW = week. LL: The last two number of LOTID.

8: YHM2008



YHMicros Website: <u>WWW.YHMICROS.COM</u>